BL-HG035A-AV-TRB

Features:

CHIP material: GaP/GaP

Emitted Color: Yellow Green

Lens Appearance: Water Clear

Mono-color type.

5. 2.0x1.25x1.0mm(0805) standard package

6. Suitable for all SMT assembly methods.

7. Compatible with infrared and vapor phase reflow solder process.

Compatible with automatic placement equipment.

This product doesn't contain restriction Substance, comply ROHS standard.

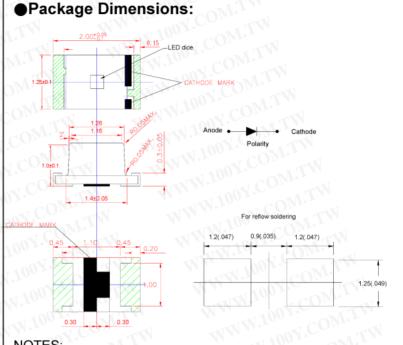
Applications:

1. Automotive: Dashboards, stop lamps, turn signals.

2. Backlighting: LCDs, Key pads advertising.

Status indicators: Comsumer & industrial electronics.

4. General use.



NOTES:

- 1.All dimensions are in millimeters (inches).
- 2. Tolerance is ± 0.10mm (0.004") unless otherwise specified.
- 3. Specifications are subject to change without notice.

特力材料886-3-5753170 胜特力电子(上海) 86-21-34970699 胜特力电子(深圳) 86-755-83298787 Http://www.100y.com.tw

Absolute Maximum Ratings(Ta=25℃)

	T AND STATE		
Parameter	Symbol	Rating	Unit
Power Dissipation	PdCON	80 COM-	mW
Forward Current	WW. Joseph COM.	30	mA
Peak Forward Current *1	I _{FP} Y.COM	100	mA
Reverse Voltage	V _R CO	5	V
Operating Temperature	Topr	-40°C ~85°C	-
Storage Temperature	Tstg	-40°C ~85°C	-
Soldering Temperature	Tsol	See Page6	-

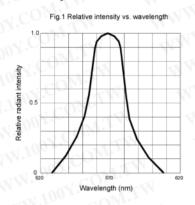
^{* 1} Condition for I_{FP} is pulse of 1/10 duty and 0.1msec width.

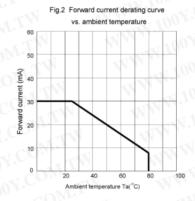
BL-HG035A-AV-TRB

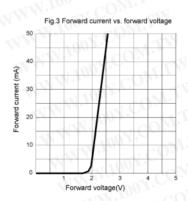
■ Electrical and optical characteristics(Ta=25°C)

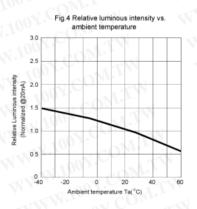
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Voltage	Vf	I _F =20mA	MMM	2.2	2.6	V
Luminous Intensity	lv ov.	I _F =20mA	3.7	12	MTW	mcd
Reverse Current	I_R	V _R =5V	- WW	W 100Y.C	100	μА
Peak Wave Length	λp	I _F =20mA	- 11	568	TW.	nm
Dominant Wave Length	λd	I _F =20mA	566	M. 100X	576	nm
Spectral Line Half-width	Δλ	I _F =20mA	N	30	COMITY	nm
Viewing Angle	2θ _{1/2}	I _F =20mA		120	T.M.T	deg

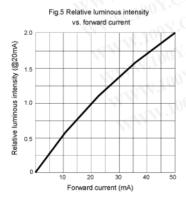
Typical Electro-Optical Characteristics Curves

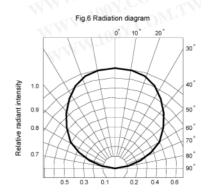






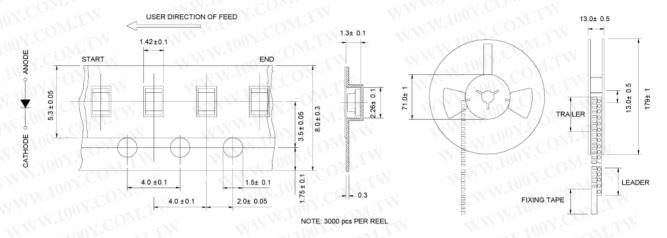




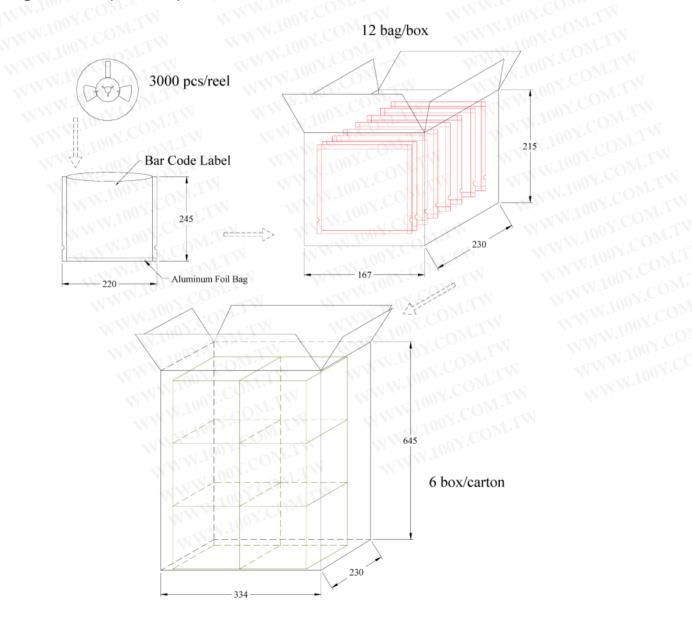


BL-HG035A-AV-TRB

Tapping and packaging specifications(Units: mm)



●Package Method:(unit:mm) Vacuum



BL-HG035A-AV-TRB

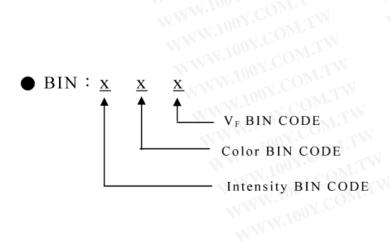
BIN CODE	Min. (mcd)	Max. (mcd)
G	3.7	5.5
Н	100 5.5	8.2
IN 1 W	8.2	12.3
TW K WW	12.3	18.5

BIN CODE	Min. (nm)	Max. (nm)
. 4	566	568
5	568 M	570
6.17	570	572
TOON. CAVILLA	572	574
100Y. 8 M.TW	574	576

V_F Bin Limits (At 20mA)

IN CODE	Min.(v)	Max.(v)	
N.1B	1.8	OM. 2.0	
CON	2.0	2.2	
DOON.	2.2	2.4	
NAF OUN CON	2.4	2.6	

Tolerance for each Bin limit is ± 0.05 V. WWW.100Y.CO WWW.100Y.COM.TW



BL-HG035A-AV-TRB

Reliability Test

Classification	Test Item	Reference Standard	Test Conditions	Result
100X.COM.	Operation Life	MIL-STD-750D:1026 MIL-STD-883D:1005 JIS-C-7021 :B-1	Connect with a power If=20mA Ta=Under room temperature Test time=1,000hrs	0/20
Endurance	High Temperature High Humidity Storage	MIL-STD-202F:103B JIS-C-7021 :B-11	Ta=+85°C±5°C RH=90%-95% Test time=240hrs	0/20
Test	High Temperature Storage	MIL-STD-883:1008 JIS-C-7021 :B-10	High Ta=+100°C±5°C Test time=1,000hrs	0/20
MMM.100	Low Temperature Storage	JIS-C-7021 :B-11	Low Ta=-40°C±5°C Test time=1,000hrs	0/20
MAN.	Temperature Cycling	MIL-STD-202F:107D MIL-STD-750D:1051 MIL-STD-883D:1010 JIS-C-7021 :A-2	-35°C±5°C ~+25°C ~+85°C±5°C ~+25°C 30min 5min 30min 5min Test Time=10cycle	0/20
Environmental Test	Thermal Shock	MIL-STD-202F:107D MIL-STD-750D:1051 MIL-STD-883D:1011	-40°C±5°C ~+85°C±5°C 20min 20min Test Time=10cycle	0/20
	Solder Resistance	MIL-STD-202:201A MIL-STD-750:2031 JIS-C-7021 :A-1	Preheating: 140°C-160°C, within 2 minutes. Operation heating: 260°C (Max.), within 10seconds. (Max.)	0/20

Judgment criteria of failure for the reliability

Measuring items	Symbol	Measuring conditions	Judgement criteria for failure
Forward voltage	$V_{F}(V)$	I _F =20mA	Initial Level*1.1
Reverse current	$I_R(uA)$	V _R =5V	Over U*2
Luminous intensity	Iv (mcd)	I _F =20mA	Initial Level*0.7

Note: 1.U means the upper limit of specified characteristics.

2.Measurment shall be taken between 2 hours and after the test pieces have been returned to normal ambient conditions after completion of each test.

BL-HG035A-AV-TRB

Soldering :

1. Manual Of Soldering

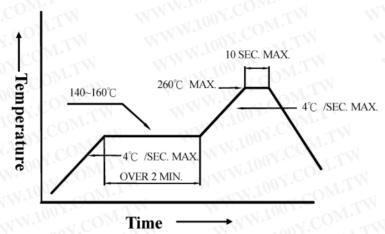
The temperature of the iron tip should not be higher than 300°C (572°F) and Soldering within 3 seconds per solder-land is to be observed.

2. Reflow Soldering

Preheating: 140°C ~160°C ±5°C, within 2 minutes.

Operation heating: 260°C (Max.) within 10 seconds.(Max)

Gradual Cooling (Avoid quenching).

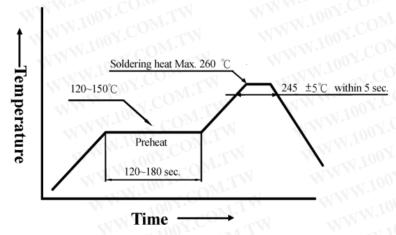


3. DIP soldering (Wave Soldering):

Preheating: 120°C~150°C, within 120~180 sec.

Operation heating: 245°C±5°C within 5 sec.260°C (Max)

Gradual Cooling (Avoid quenching).



Handling:

Care must be taken not to cause to the epoxy resin portion of BRIGHT LEDs while it is exposed to high temperature.

Care must be taken not rub the epoxy resin portion of BRIGHT LEDs with hard or sharp article such as the sand blast and the metal hook.

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